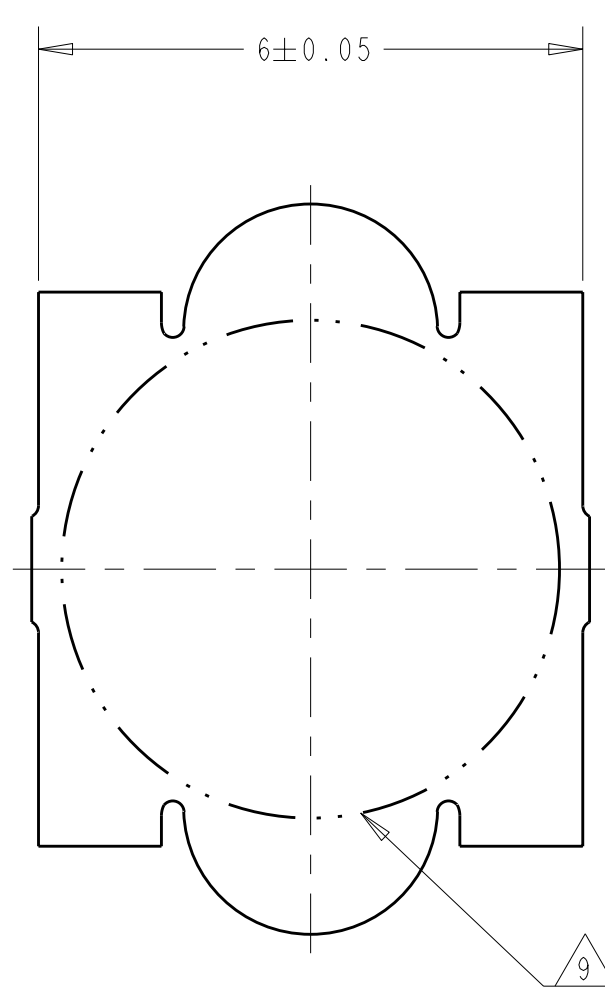
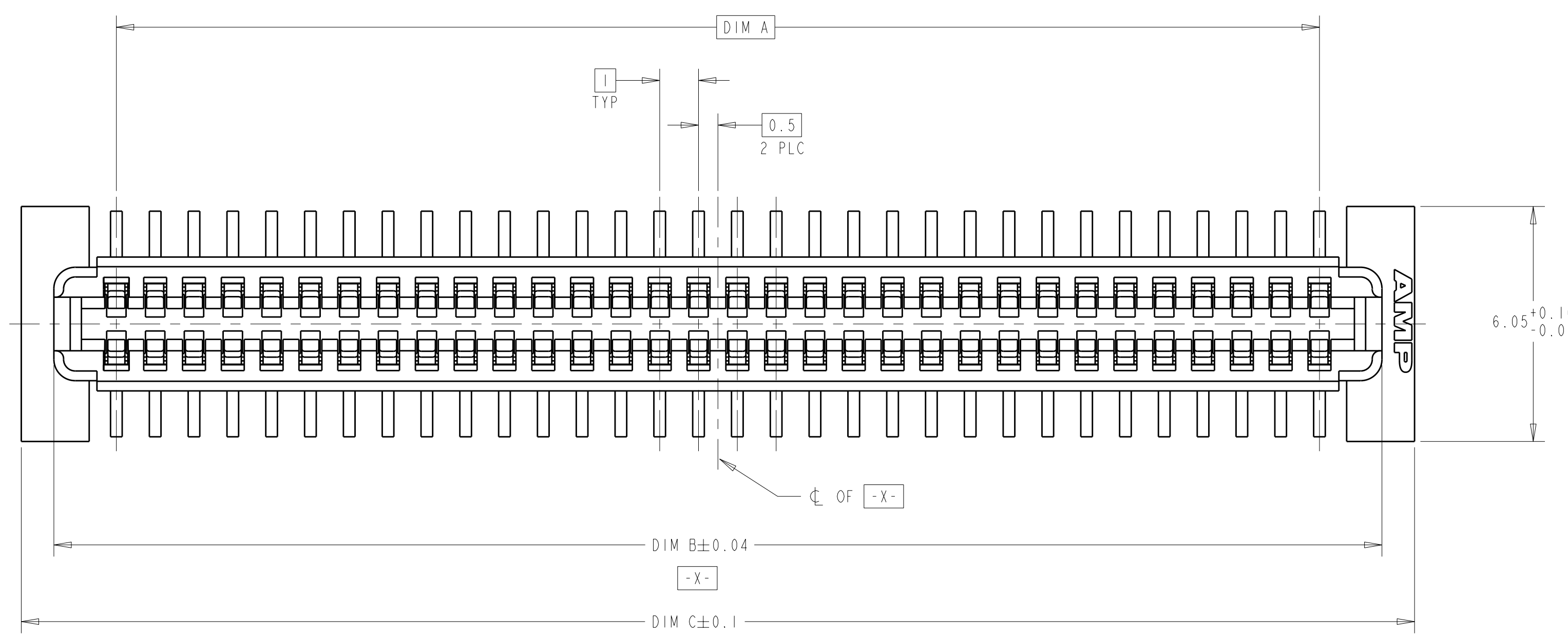
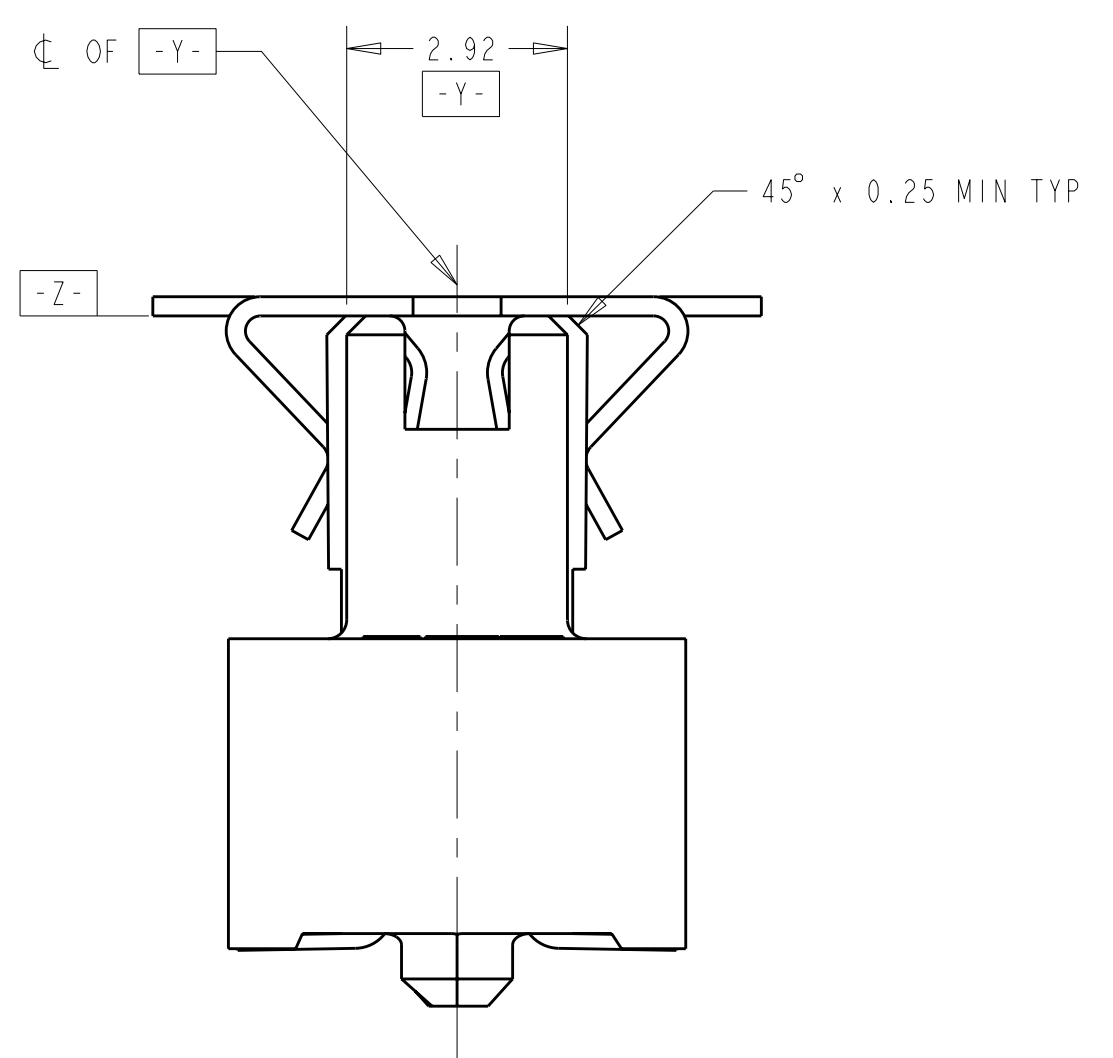
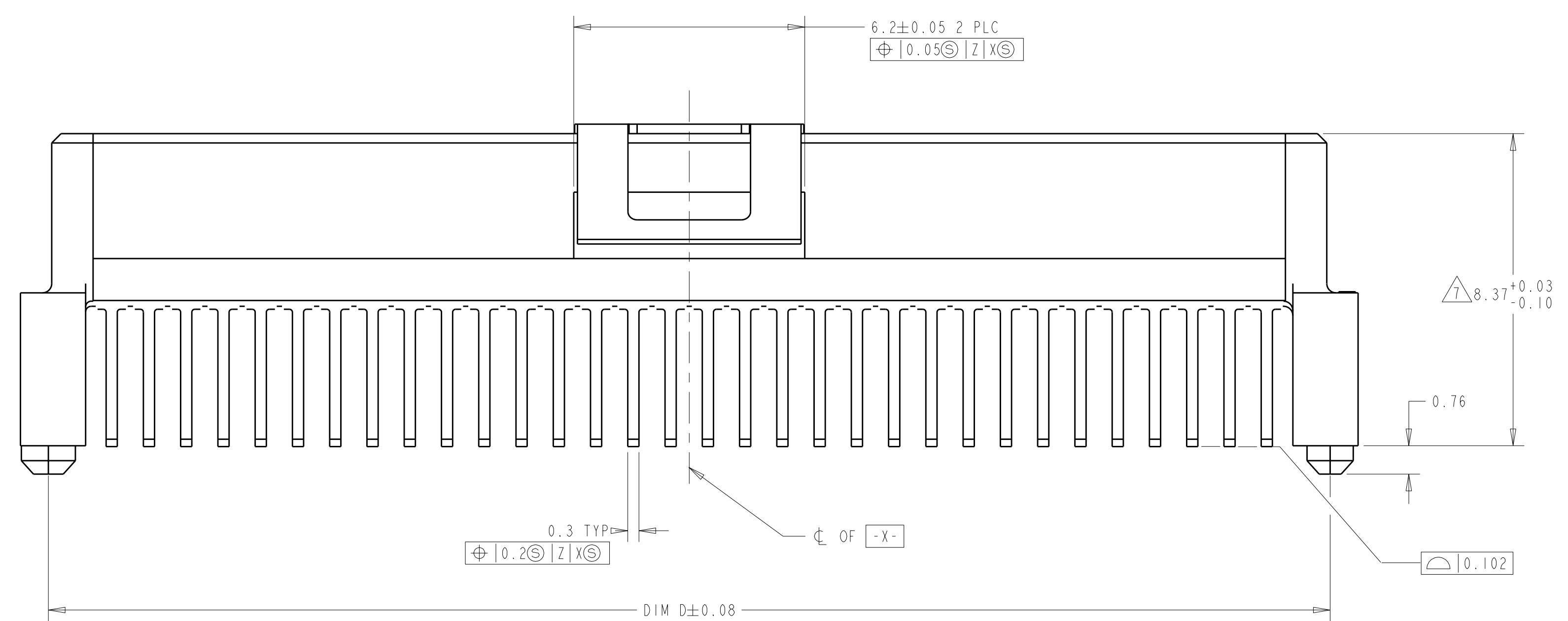


LOC	DIST	REV	DATE	BY	CHK	APPD
AD	00	H	12FEB2004	RWS	RHW	
		J	06FEB2007	BC	DB	
		K	10JUL2008	DH	DB	
		K1	26AUG2009	AEG	DD	

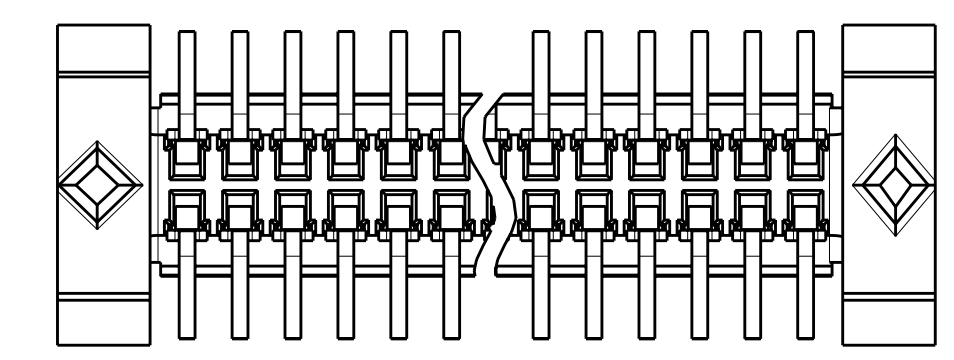


VACUUM COVER

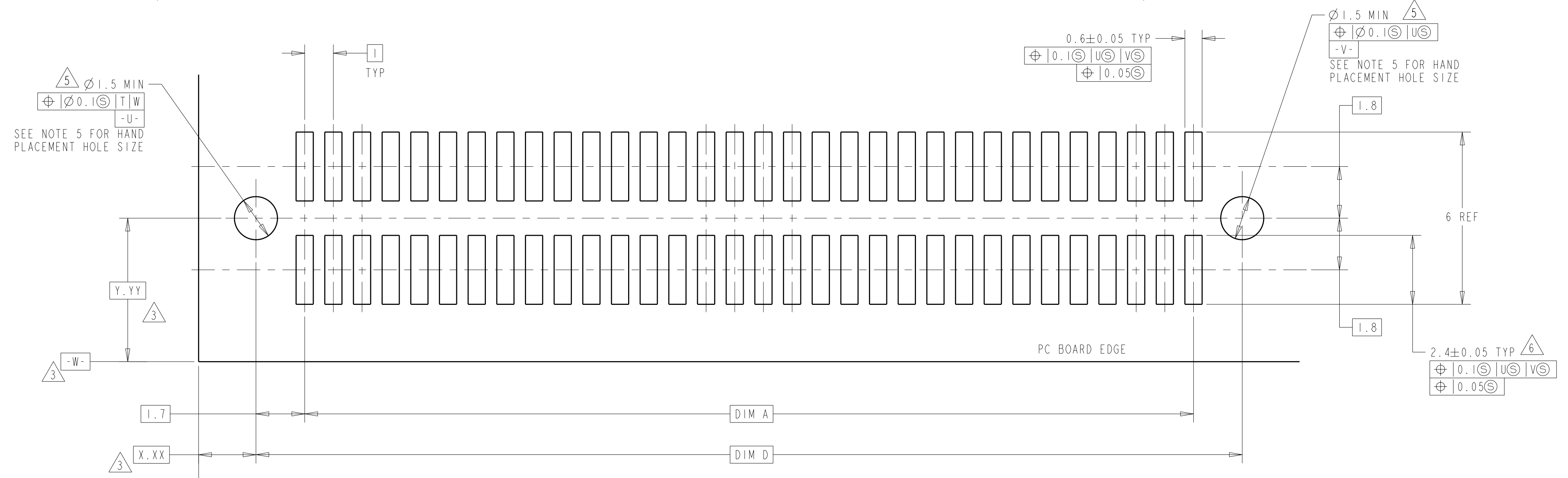
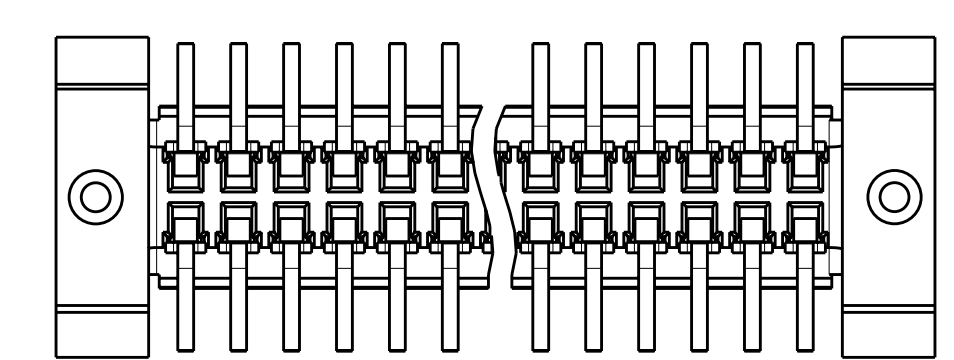
- HOUSING MATERIAL: HIGH TEMPERATURE THERMOPLASTIC, COLOR: BLACK.) CONTACT MATERIAL: PHOSPHOR BRONZE.
- CONTACT FINISH: NICKEL UNDERPLATE ALL OVER, MATING SURFACES PLATED TO MEET PL1 PERFORMANCE REQUIREMENTS OF INDUSTRY SPECIFICATION EIA-700AAAB, SOLDER TAILS PLATED TIN-LEAD.
- DATUM LOCATIONS AND BASIC DIMENSIONS TO BE ESTABLISHED BY THE CUSTOMER. CONSULT AMP ENGINEERING WHEN PLACING MULTIPLE CONNECTORS ON A PC BOARD.
- PACKAGED IN TAPE ON REEL PER EIA-481.
- 1.4 ± 0.05 DIAMETER HOLE WHEN PLACING BY HAND.
- SHORTER SOLDER LANDS MAY BE USED PER EIA 700AAAB, HOWEVER 2.4 LENGTH ASSURES OPTIMUM SOLDER FILLET REGARDLESS OF MANUFACTURER OF CONNECTOR.
- REFERRED TO AS DIM H = 8.3 ± 0.1 IN EIA 700AAAB SPECIFICATION.
- VACUUM COVER NOT SHOWN IN SOME VIEWS FOR CLARITY.
- 5.5 MIN DIAMETER TARGET AREA FOR VACUUM PICK-UP.
- CONTACT FINISH: 0.00381 MINIMUM MATTE TIN-LEAD (93-7) ON SOLDER AREA, 0.00127 MINIMUM GOLD ON MATING AREA, BOTH OVER 0.00127 MINIMUM NICKEL ON ENTIRE CONTACT.
- SQUARE AND DIAMOND SHAPED POSTS.
- ROUND SHAPED POSTS.



STYLE A POSTS



STYLE B POSTS



RECOMMENDED PC BOARD LAYOUT

POST STYLE	FINISH	DIM D	DIM C	DIM B	DIM A	STACK HEIGHTS	POS	AMP PART NUMBER
12	10	44.4	45.9	44.22	41	13	84	3-146895-2
12	10	34.4	35.9	34.22	31	13	64	3-146895-1
12	2	44.4	45.9	44.22	41	13	84	2-146895-2
12	2	34.4	35.9	34.22	31	13	64	2-146895-1
11	10	44.4	45.9	44.22	41	13	84	1-146895-2
11	10	34.4	35.9	34.22	31	13	64	1-146895-1
11	2	44.4	45.9	44.22	41	13	84	146895-2
11	2	34.4	35.9	34.22	31	13	64	146895-1

TYCO ELECTRONICS CORPORATION
 HARRISBURG, PA 17105-3608

NAME: RECEPTACLE ASSY, W/ VACUUM COVER, 1.0mm FH(IEEE 1386) CONNECTOR

SIZE: 114-25045 CAGE CODE: 00779 DRAWING NO: 502-1079

SCALE: 10:1 SHEET 1 OF 1 REV: K1